IN THE CLAIMS

1. (currently amended) A method for marking a wafer that is cut from a boule, the method comprising the sequential steps of:

marking a surface of the boule with ~~an~~ encoded markings that extends ~~completely~~ substantially contiguously along a distance of the boule that is used for cutting wafers, where the encoded markings ~~is~~ are disposed substantially parallel to a length axis of the boule, and

cutting the wafer from the boule from within the distance, such that the encoded markings along the surface of the boule ~~is~~ are disposed at a peripheral edge of the wafer,

where the encoded markings contains information in regard to the wafer.

2. (original) The method of claim 1, further comprising the step of rounding the peripheral edge of the wafer in a manner that does not remove the encoded marking.

3. (original) The method of claim 1, wherein the wafer is formed of a semiconducting material.

4. (original) The method of claim 1, wherein the wafer is formed of at least one of silicon, germanium, and a III-V compound.

5. (original) The method of claim 1, wherein the step of marking the surface of the boule comprises laser ablating substantially parallel lines in the surface of the boule.

6. (original) The method of claim 1, wherein the step of marking the surface of the boule comprises printing substantially parallel lines on the surface of the boule.

7. (original) The method of claim 1, further comprising the step of rounding the surface of the boule prior to marking the surface of the boule.

8. (currently amended) The method of claim 1, wherein the encoded markings comprises a bar code.

9. (original) The method of claim 1, wherein the information includes at least one of an index number, a wafer manufacturer identification, a date of manufacture, a location of manufacture, and a boule identification.

10. (currently amended) The method of claim 1, further comprising the step of adding to the encoded markings on the wafer, a wafer identification that is unique relative to the boule, after the step of cutting the wafer from the boule.

11. (original) A wafer marked by the method of claim 1.

12. (currently amended) A method for identifying a wafer that is cut from a boule, the method comprising the sequential steps of:

marking a surface of the boule with ~~an~~ encoded markings that ~~extends~~ substantially contiguously ~~completely~~ along a distance of the boule that is used for cutting wafers, where the encoded markings ~~is~~ are disposed substantially parallel to a length axis of the boule,

cutting the wafer from the boule from within the distance, such that the encoded markings along the surface of the boule is disposed at a peripheral edge of the wafer,

where the encoded markings contains information in regard to the wafer, and

reading the encoded markings on the peripheral edge of the wafer to identify the wafer.

13. (original) The method of claim 12, wherein the wafer is formed of a semiconducting material.

14. (original) The method of claim 12, wherein the step of marking the surface of the boule comprises laser ablating substantially parallel lines in the surface of the boule.

15. (currently amended) The method of claim 12, wherein the encoded markings comprises a bar code.

16. (currently amended) The method of claim 12, further comprising the step of adding to the encoded markings on the wafer, a wafer identification that is unique relative to the boule, after the step of cutting the wafer from the boule.

17. (currently amended) A method for positioning a wafer that is cut from a boule in a known physical orientation, the method comprising the sequential steps of:

marking a surface of the boule with ~~an~~ encoded markings that extends substantially contiguously ~~completely~~ along a distance of the boule that is used for cutting wafers, where the encoded markings ~~is~~ are disposed substantially parallel to a length axis of the boule, and where the encoded markings ~~is~~ are disposed at a known location relative to a physical orientation of the boule,

cutting the wafer from the boule from within the distance, such that the encoded markings along the surface of the boule is disposed at a peripheral edge of the wafer,

rotating the wafer,

detecting the encoded markings on the peripheral edge of the wafer as the wafer rotates, and

stopping the rotation of the wafer when the encoded markings on the peripheral edge of the wafer ~~is~~ are disposed in a desired position.

18. (original) The method of claim 17, wherein the step of marking the surface of the boule comprises laser ablating substantially parallel lines in the surface of the boule.

19. (currently amended) The method of claim 17, wherein the encoded markings comprises a bar code.

20. (currently amended) The method of claim 17, further comprising the step of adding to the encoded markings on the wafer, a wafer identification that is unique relative to the boule, after the step of cutting the wafer from the boule.